# **WJA1001** +5V Active-Bias InGaP HBT Gain Block

# **Product Features**

- 50 3000 MHz
- 19 dB Gain @ 900MHz
- www.ett 20 dBm P1dB @ 900MHz
  - +45 dBm OIP3 @ 900MHz
  - +5V Single Supply
  - Low current draw (100 mA)
  - Unconditionally stable
  - Internally matched to 50  $\Omega$
  - Robust 1000V ESD, Class 1C
  - Lead-free/green/RoHS-compliant SOT-89 package

# **Applications**

- GSM, PCS, CDMA, WCDMA
- WiMAX, WiBro
- Repeaters, BTS Transceivers
- RFID

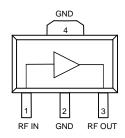
# **Product Description**

The WJA1001 is a cascadable gain block that offers high linearity in a low-cost surface-mount package. At 900 MHz, the WJA1001 typically provides 19 dB gain, +45 dBm OIP3, and +20 dBm P1dB. The device is housed in a lead-free/green/RoHS-compliant SOT-89 SMT package using a NiPdAu plating to eliminate the possibility of tin whiskering.

The WJA1001 consists of a Darlington-pair amplifier using a high reliability InGaP/GaAs HBT process technology. The amplifier has been optimized internally to offer very high linearity performance at 1 GHz while drawing very low current. The MMIC amplifier is internally matched to  $50\Omega$  and only requires DC-blocking capacitors and a bias inductor for operation. An internal active bias is designed to enable stable performance over temperature and allow for operation directly from a +5V supply voltage.

The broadband amplifier can be directly applied to various current and next generation wireless technologies such as GSM, CDMA, W-CDMA, WiBro, and WiMAX. The WJA1001 is ideal for general purpose applications such as LO buffering or amplification and pre-driver stages within the 50 to 3000 MHz frequency range.

# **Functional Diagram**



Function	Pin No.
Input	1
Output/Bias	3
Ground	2, 4

# Specifications<sup>(1)</sup>

Parameter	Units	Min	Тур	Max
Operational Bandwidth	MHz	50		3000
Test Frequency	MHz		900	
Gain	dB		19	
Input Return Loss	dB		12	
Output Return Loss	dB		14	
Output P1dB	dBm		+19.7	
Output IP3 <sup>(2)</sup>	dBm		+44.5	
Noise Figure	dB		5.4	
Device Voltage	V		5.0	
Device Current	mA		100	

1. Test conditions: 25 °C, Supply Voltage = +5 V, 50  $\Omega$  System. S-parameters and 30IP measured at device pins. All other specifications measured on evaluation board.

 3OIP measured with two tones at an output power of +8 dBm/tone separated by 1 MHz. The suppression on the largest IM3 product is used to calculate the 3OIP using a 2:1 rule.

# Typical Performance<sup>(3)</sup>

Parameter	Units			Гуріса	al	
Frequency	MHz	200	500	900	1900	2100
S21	dB	19.6	19.2	18.5	16.7	16.4
S11	dB	-13	-15	-18	-30	-26
S22	dB	-22	-20	-15	-11	-12
Output P1dB	dBm	+20.4	+20.3	+19.7	+19.2	+18.1
Output IP3 <sup>(2)</sup>	dBm	+39.7	+39	+44	+34	+34
Noise Figure	dB	4.8	5.0	5.4	6.1	6.4

3. Listed typical performance parameters measured on evaluation board.

# **Absolute Maximum Rating**

Parameter	Rating
Storage Temperature	-55 to +150 °C
Supply Voltage	+6.5 V
Input Power	+24 dBm
$\theta_{ic}$ (junction to paddle)	80.6 °C / W
Maximum Junction Temperature	150 °C

# **Ordering Information**

Part No.	Description
WJA1001	+5V Active Bias InGaP HBT Gain Block (lead-free/green/RoHS-compliant SOT-89 Package)
WJA1001-PCB	50-3000 MHz Fully Assembled Eval. Board

Operation of this device above any of these parameters may cause permanent damage.

Standard tape / reel size = 1000 pieces on a 7" reel

Specifications and information are subject to change Without notice[] []]

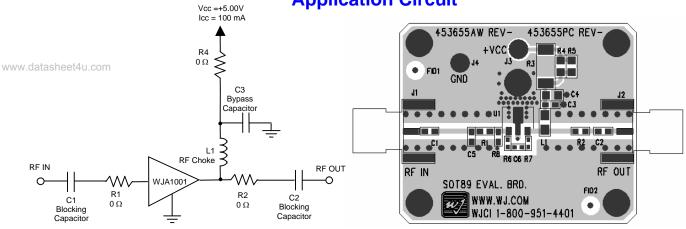


#### Gain vs. Frequency Return Loss vs. Frequency NF vs. Frequency 10 25 0 www.datashe -5 20 8 -10 S11, S22 (dB) **Gain (dB)** 10 -15 (gp)<sup>6</sup> Ĕ, -20 -25 5 2 -30 • • S11 -S22 -35 0 0 1000 20 Frequency (MHz) 0 2000 3000 0 1000 2000 Frequency (MHz) 3000 1000 2000 Frequency (MHz) 0 3000 OIP3 vs. Vcc Frequency=900MHz, T=25C OIP3 vs. Output Power Frequency=900MHz, T=25C OIP3 vs. Frequency Pout = 8dBm/tone 45 45 45 40 40 40 OIP3 (dBm) S2 OIP3 (dBm) OIP3 (dBm) 30 30 30 ···-- 40C --- +85C 25 25 25 4.9 5 Supply Voltage (V) 4 6 8 Output Power per tone (dBm) 0 12 4.7 4.8 5.1 5.2 2 10 3000 0 1000 2000 Frequency (MHz) ICC vs. VCC Frequency=900MHz, T=25C P1dB vs. Vcc Frequency = 900MHz, T = 25C P1dB vs. Frequency 22 120 22 110 20 20 **H14B (dBm) B14B** 100 **H1dB (dBm)** 16 lcc (mA) 80 14 14 ···-40C --- +25C --- +85C 70 12 60 12 4.7 4.8 5.1 5.2 49 5 0 1000 2000 3000 4.7 4.8 4.9 5 5.1 5.2 Frequency (MHz) Supply Voltage (V) Supply Voltage (V)

# Typical Evaluation Board RF Performance Supply Bias = +5V, I<sub>cc</sub> = 100 mA



a b



### **Application Circuit**

#### **<u>Recomm</u>ended Component Values**<sup>(1)</sup>

Ref. Name	Value / Type	Size
L1	470 nH ferrite core wire wound inductor <sup>(2)</sup>	0805
C1, C2	1000 pF NPO chip capacitor	0603
C3	0.018 µF chip capacitor	0603
R1, R2, R4	$0  \Omega^{(3)}$	0603
C4, C5, C6,	Do Not Place <sup>(3)</sup>	
R3, R5, R6,		
R7, R8		
1. The listed valu	ies are contained on the evaluation board to achieve optimal	l broadband j

The listed values are contained on the evaluation board to achieve optimal broadband performance

2. For lower cost and performance (500 - 2000 MHz) option use 39 nH ceramic core wire wound inductor.

3. Place holders for the  $0\Omega$  resistors and "Do Not Place" references are not needed for final design.

# **Typical Device Data**

S-Parameters (V	$V_{\text{device}} = +5 \text{ V}, \text{ I}_{\text{C}}$		= 25 °C, calibra		ads)			
Freq (GHz)	S11 (dB)	S11 (ang)	S21 (dB)	S21 (ang)	S12 (dB)	S12 (ang)	S22 (dB)	S22 (ang)
10	-16.19	-74.53	22.52	170.02	-25.75	12.97	-11.35	-37.50
50	-13.73	-150.31	20.24	167.55	-23.34	6.00	-17.22	-110.83
100	-13.40	-165.59	19.82	167.74	-23.16	2.19	-18.78	-136.33
200	-13.27	-173.49	19.60	162.77	-23.09	-1.09	-19.05	-148.58
400	-12.67	-178.71	19.50	149.81	-23.01	-4.76	-18.29	-151.10
600	-12.13	177.74	19.35	136.50	-22.97	-8.79	-17.08	-151.78
800	-11.99	172.41	19.15	122.68	-22.90	-12.46	-15.70	-150.91
1000	-12.07	163.93	18.99	109.45	-22.85	-16.03	-13.92	-151.81
1200	-12.02	152.87	18.73	94.83	-22.84	-19.42	-12.73	-157.08
1400	-11.71	142.18	18.33	81.54	-22.75	-23.24	-11.59	-165.19
1600	-11.76	132.89	18.10	67.63	-22.81	-27.41	-10.74	-173.87
1800	-12.61	125.70	17.71	53.78	-22.66	-30.65	-9.99	179.93
2000	-14.95	116.23	17.35	40.27	-22.75	-35.01	-9.15	175.81
2200	-18.89	100.16	16.88	26.53	-22.71	-38.53	-8.48	171.38
2400	-24.73	70.36	16.27	12.71	-22.78	-41.54	-8.13	165.83
2600	-32.51	32.55	15.76	-1.15	-22.67	-45.93	-8.09	157.59
2800	-28.92	-123.80	15.14	-14.50	-22.65	-49.54	-8.09	148.86
3000	-18.69	-139.28	14.31	-28.11	-22.55	-53.67	-7.84	140.92
3200	-13.74	-143.12	13.44	-41.58	-22.62	-57.98	-7.43	135.57
3400	-10.86	-145.10	12.37	-53.94	-22.64	-61.93	-7.02	130.30
3600	-9.38	-150.89	11.40	-65.62	-22.59	-65.84	-6.80	126.09
3800	-8.61	-162.51	10.54	-76.54	-22.46	-69.00	-6.67	121.50
4000	-7.74	-178.88	9.54	-88.57	-22.15	-73.94	-6.65	116.69

Device S-parameters are available for Download from the website at: http://www.wj.com

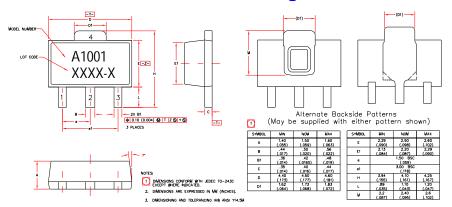


# **Mechanical Information**

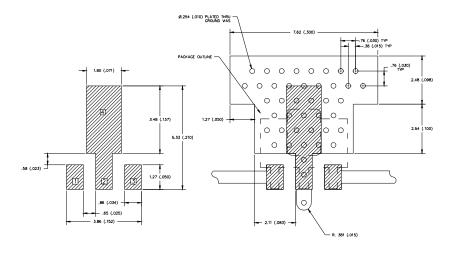
This package is lead-free/Green/RoHS-compliant. It is compatible with both lead-free (maximum 260 °C reflow temperature) and leaded (maximum 245 °C reflow temperature) soldering processes. The plating material on the leads is NiPdAu.

www.datasheet4u.com

## **Outline Drawing**



# Land Pattern



# **Product Marking**

The WJA1001 will be marked with an "A1001" designator with an alphanumeric lot code marked below the part designator.

Tape and reel specifications for this part are located on the website in the "Application Notes" section.

# **MSL / ESD Rating**

Caution! ESD sensitive device.

ESD Rating:	Class 1C
Value:	Passes $\geq 1000V$ min.
Test:	Human Body Model (HBM)
Standard:	JEDEC Standard JESD22-A114

#### ESD Rating: Class IV

LOD Humg.	0140011
Value:	Passes $\geq 1000$ V min.
Test:	Charged Device Model (CDM)
Standard:	JEDEC Standard JESD22-C101

MSL Rating: Level 3 at +260 °C convection reflow Standard: JEDEC Standard J-STD-020

# **Mounting Config. Notes**

- 1. Ground / thermal vias are critical for the proper performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
- 2. Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.
- 3. Mounting screws can be added near the part to fasten the board to a heatsink. Ensure that the ground / thermal via region contacts the heatsink
- 4. Do not put solder mask on the backside of the PC board in the region where the board contacts the heatsink.
- 5. RF trace width depends upon the PC board material and construction.
- 6. Use 1 oz. Copper minimum.
- 7. All dimensions are in millimeters (inches). Angles are in degrees.